



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-06-27
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STH300NH02L-6	R2(4*4L2KA52	A	SH1A	2016-06-27
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	10.2 - 9.15 - 4.5	7	Through-hole	
Comment	Package: H2PAK 6 LEADS			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	R2(4*4L2KA52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.653	mg	supplier	die	Silicon (Si)	7440-21-3		15.005	mg	958602	10873
				supplier	metallization	Titanium (Ti)	7440-32-6		0.383	mg	24468	278
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.09	mg	5750	65
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.009	mg	575	7
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.112	mg	7155	81
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.008	mg	511	6
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.046	mg	2939	34
Leadframe	Copper & its alloys	609.595	mg	supplier	alloy	Copper (Cu)	7440-50-8		607.6	mg	996727	440290
				supplier	alloy	Iron (Fe)	7439-89-6		0.28	mg	459	203
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.511	mg	838	370
				supplier	metallization	Nickel (Ni)	7440-02-0		1.197	mg	1964	867
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	11	5
Soft solder	Solder	11.686	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	11.16	mg	954989	8087
				supplier	solder	Silver (Ag)	7440-22-4		0.292	mg	24987	212
				supplier	solder	Tin (Sn)	7440-31-5		0.234	mg	20024	170
Bonding wire +ribbon	Other inorganic materials	16.943	mg	supplier	wire + ribbon	Aluminium (Al)	7429-90-5		16.941	mg	999882	12276
				supplier	wire	Magnesium (Mg)	7439-95-4		0.002	mg	118	1
Encapsulation	Other inorganic materials	724.033	mg	supplier	mold compound	Silica, vitreous	60676-86-0		579.225	mg	799998	419728
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		50.682	mg	70000	36726
				supplier	mold compound	Phenol resin	9003-35-4		28.962	mg	40001	20987
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		43.442	mg	60000	31480
				supplier	mold compound	Antimony Trioxide	1309-64-4		8.689	mg	12001	6296
				JIG R	mold compound	Brominated Epoxy Resin	40039-93-8		10.861	mg	15001	7870
Connections coating	Other inorganic materials	2.09	mg	supplier	mold compound	Carbon Black	1333-86-4		2.172	mg	3000	1574
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.09	mg	1000000	1514